

# TERMINATION CVD DIAMOND CHIP 10 WATTS

DATA SHEET

PART SERIES: CT0402D

SHEET 1 OF 2  
Dwg 1011105

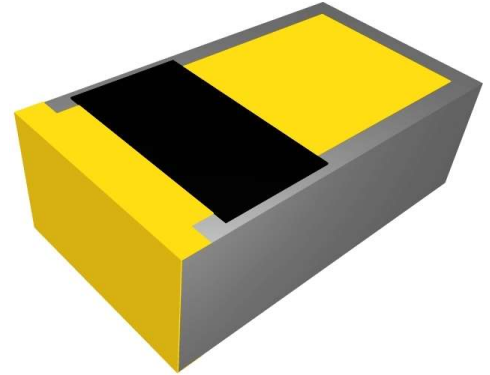
EN 18-0166  
Revision A

## FEATURES

- Small Size - Light Weight
- Highest Thermal Performance Possible
- Excellent Peak Power Capability
- Rugged Passivated TaN Film
- Moisture Resistant
- Pure Gold Input Pads
- Wire Bondable or Solderable
- High Power

## APPLICATIONS

- Broadcast
- Higher Power Filters
- High Power Amplifiers
- Instrumentation
- Isolators
- Military
- Satellite Communications
- Phased Array Radar



## GENERAL DESCRIPTION

CVD Diamond Chip Terminations offer a unique combination of extreme high power ratings in very small packages. These terminations may be used in applications up to 30 GHz and are ideal for applications with requirements for high power capability, broad frequency response, small footprint and light weight. The terminations are manufactured using all thin film construction and have a gold finish that it both wire bondable and solderable. This total thin film construction also makes them ideal for peak power applications. High reliability tested versions based on MIL-PRF-55342 are also available. Select from tape and reel, bulk, or waffle packaging. These products are also lead free, RoHS compliant and S-level approved.

## ORDERING INFORMATION

Part Identifier: **CT0402D**

## SPECIFICATIONS

### 1.0 ELECTRICAL

Nominal Impedance:	50 $\Omega \pm 5\%$
Frequency Range:	DC – 26.5 GHz
Input Power CW:	10 Watts
Peak Power:	100 Watts (1 $\mu$ s pulse width/1% duty cycle)
VSWR:	DC - 8.0 GHz 1.35:1 8.0 – 12.4 GHz 1.50:1 12.4 – 18.0 GHz 1.70:1 18.0 – 26.5 GHz 1.95:1

### 2.0 ENVIRONMENTAL

Operating Temperature:	-55 °C To 150 °C
Storage Temperature:	-55 °C To 150 °C
Temperature Coefficient:	$\pm 200$ PPM/°C Max

### 3.0 MARKING

Unit Marking:	None
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### 4.0 QUALITY ASSURANCE

Sample Inspect Per ANSI/ASQC Z1.4 General Inspection, Level II, 1.0% AQL.  
Visual and Mechanical Inspection for Conformance to Outline Drawing  
Measure DC Resistance  
Data Retention - Standard

### 5.0 PACKAGING

Standard:	Waffle Packaging
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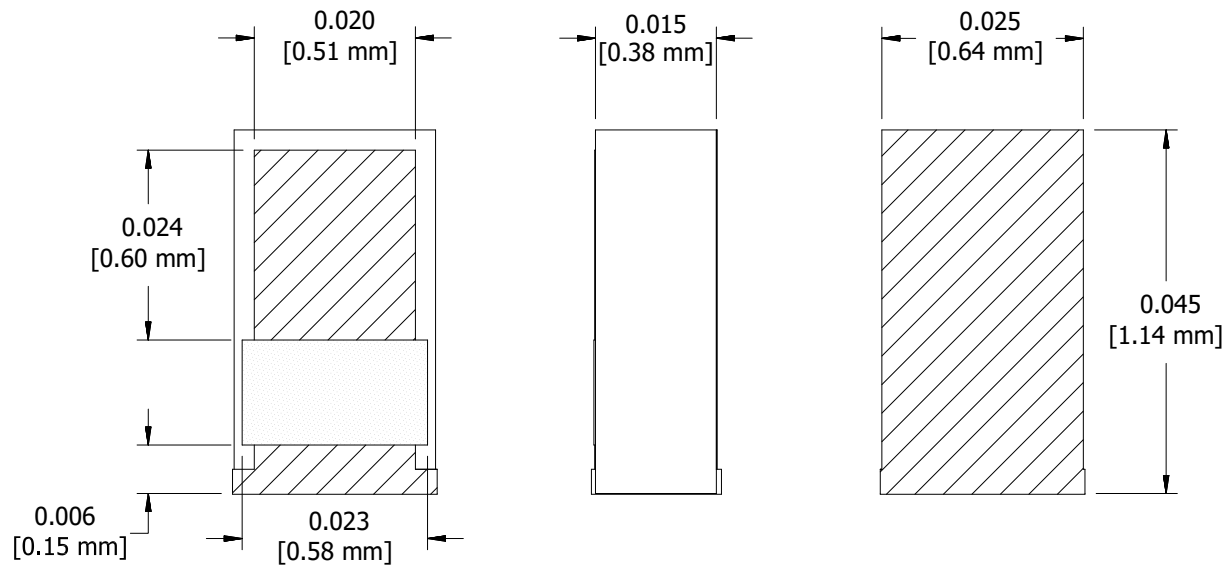
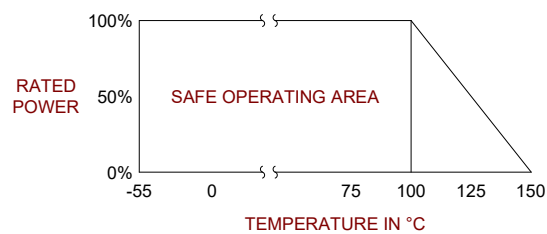
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## 6.0 MECHANICAL

Substrate Material:	CVD Diamond
Terminal Material:	Gold over Nickel
Ground Plane Material:	Gold over Platinum
Resistive Element:	Thin Film
Metric Dimensions:	Provided for reference only



Unless Otherwise Specified: TOLERANCE: X.XX =  $\pm 0.01$  X.XXX =  $\pm 0.005$